

# Fully Electric from 0 to 100 in less than 3 seconds!

Remi Jonkman | Electric Superbike Twente  
Marcel Wezenberg | CB Distribution

**DESIGN AUTOMATION  
& EMBEDDED SYSTEMS**

FPGA - SECURITY - INTERNET OF THINGS - ELECTRONIC DESIGN & PRODUCTION - EMBEDDED - DESIGN FOR EXCELLENCE - EMBEDDED DESIGN CHALLENGES

**7 NOV** ←  
TECHNOPOLIS, MECHELEN

**8 NOV** ←  
VAN DER VALK HOTEL, EINDHOVEN



# Agenda

- CB Distribution
- Electric Superbike Twente
- Design challenges
- Use of EDA Tools
- Results

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# CB Distribution

- Cadence Channel Partner for the Benelux, Spain and Portugal
- Focused on System, IC, Package and PCB solutions
  - OrCAD
  - Allegro
  - Virtuoso
- Training
  - Tool and methodology
- CAD Support
  - Environment setup
  - Setup and maintenance of data transfer
  - Conversions

# Electric Superbike Twente

- 15 students
- Goals:
  - Show how epic electric motorcycles are!
  - Winning the MotoE competition.
    - Thus beating TUDelft
  - Collaborate in a large multidisciplinary team.



# Challenges

- Electrical System
- Mechanical System
- Finance
- Planning
- Short Development Phase

# Planning

September 2017	<b>Design</b>
December 2017	<b>Production</b>
March 2018	<i>Official Release</i>
May 2018	<b>Testing</b>
July 2018	<b>First Race</b>



# Top Level Requirements

- Power: 150 kW
- Maximum Voltage: 700 VDC
- Top speed: 250 km/h
- Torque: 500 Nm
- Capacity: 8-12 laps
- Maximum weight: 200 kg
- Water and Dust Proof



# Design Choices

## Stock components

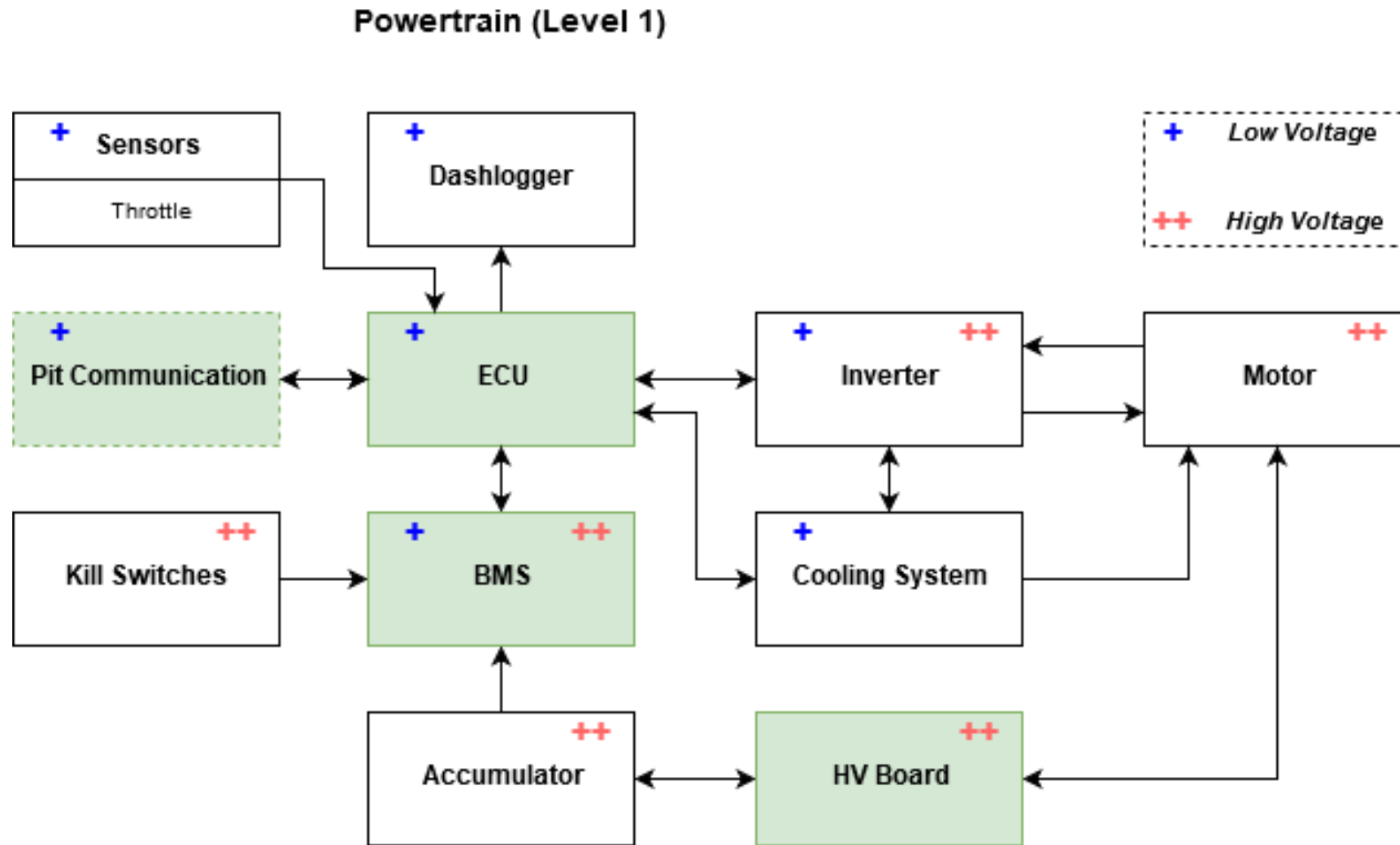
- ✓ Plug and play
- ✓ Support
- ✓ Availability
- ✓ Cost

## Self-made components

- ✓ Flexibility
- ✓ Cost
- ✗ Time expensive
- ✗ Potentially buggy



# Electrical System – High Level



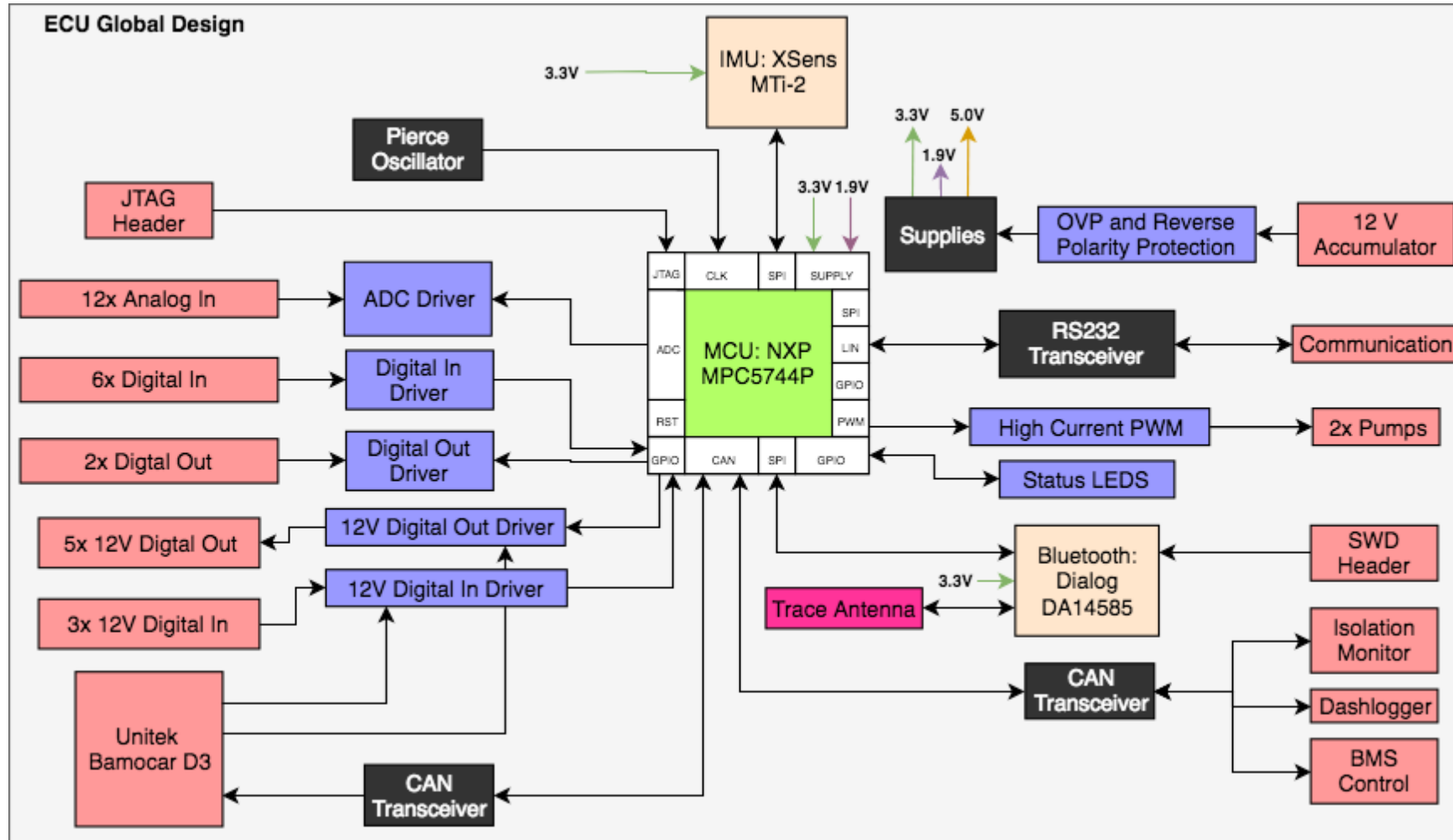
# Safety

- What if throttle cable malfunctions at 200 km/h?
- What if there's an under voltage in the high voltage battery pack?
- Fail Scenario's
  - Driver safety first
- Automotive Grade ECU
  - Component selection

# Subsystems

- Analog
- Digital In/Out
- 12V Digital In/Out
- Communication
  - JTAG (Debugging)
  - CAN
  - SPI
  - UART (RS232)
- Bluetooth
- Power Supplies
  - 1.9 V
  - 3.3 V
  - 5.0 V
- Overvoltage Protection
- Reverse Polarity Protection
- Microprocessor

# Subsystems – Block Diagram



# Mixed Signal Circuit Simulation

- Why simulation?
  - Verify our design choices
    - Functionality
    - Reliability
  - Quick compared to hardware production process
    - A lot of PSpice models available



# Tools Used

- OrCAD Capture
- PSpice
- OrCAD PCB Editor
  - Padstack Editor
  - Constraint Areas



# Use of EDA Tools

- Mixed Signal Circuit Simulation
  - Simulation models
  - Reliability Analysis
- PCB Design
  - Constraints
  - 3D View
  - Multi board verification



# Use of EDA Tools

## *Simulation models*

- There
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- Differ
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- No
- M
- Spice
- Te
- Re

## SPICE Model of Polyswitch Device

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**Abstract**—Polymer Positive Temperature Coefficient thermistor (PPTC) as a polyswitch for circuit protection is not a standard circuit element for SPICE simulation, which hinders circuit performance evaluation and prediction. Physics-based model written in SPICE engine is of advantage in speed and accuracy, however, it is impractical for every device engineers to build a physical theory and rewrite a SPICE engine to simulate a new device. This report illustrates a novel circuit architecture with pre-existing SPICE elements for PPTC simulation. Three types of PPTCs, miniSMDC014F, miniSMDC050F, miniSMDC150F-24, offered by TE Connectivity, are verified for this method. The related data and netlist, including library usage, are provided.

**Index Terms**—SPICE model, polyswitch, curve fitting, positive temperature coefficient thermistor (PTC).

however, the proposed netlist can't adapt itself to different ambient temperature and fault current, limiting the simulation flexibility of the SPICE model.

This report demonstrates a novel circuit structure for PPTC SPICE model with switching and tripping behaviour, suitable for various ambient temperature and fault current. The article is organized as follows. Section II reviews some fundamental parameters and related definitions of PPTC, and also discusses the curve fitting procedure for parameter extraction. The entire circuit system for PPTC model is illustrated and analyzed in Section III. Several experimental examples are given in Section IV to validate the effectiveness of the SPICE model in OrCAD PSPICE. Section V concludes the paper.

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# Use of EDA Tools

## *Reliability Analysis*

- Sensitivity
- Monte Carlo
- Stress Analysis, “Smoke”

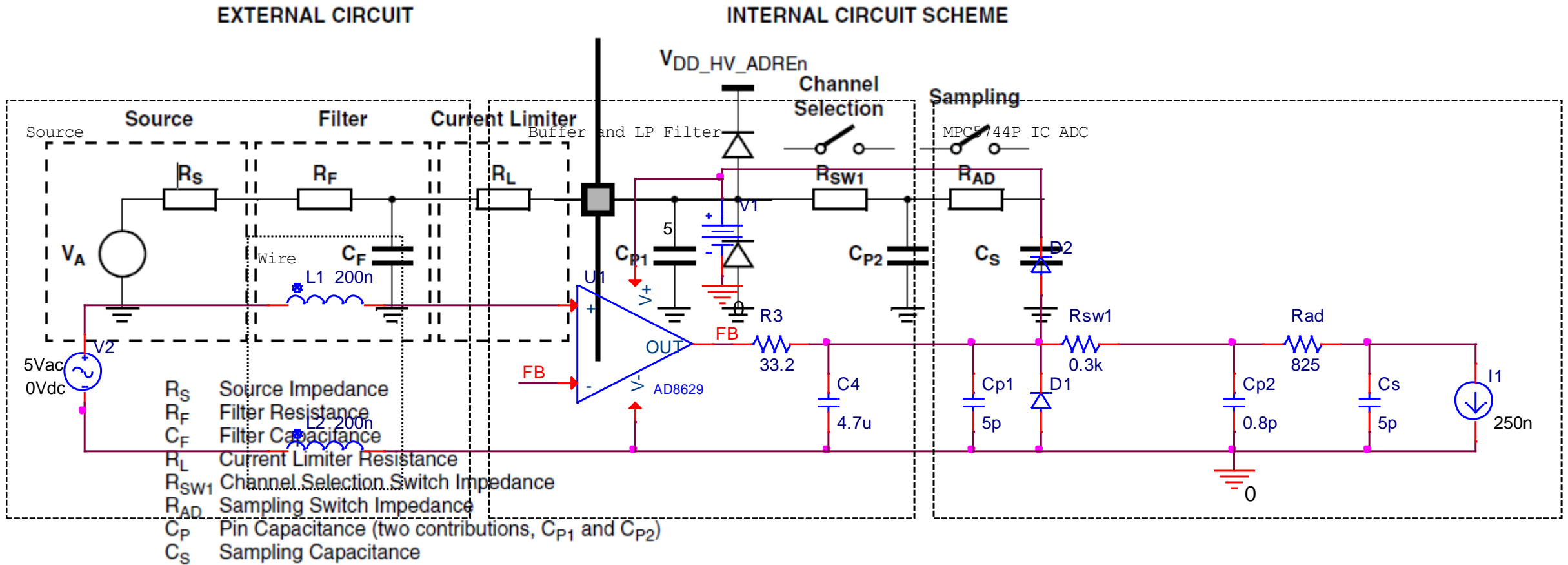


# Use of EDA Tools

## *Reliability: Sensitivity Analysis*

- Find parts with most impact on Specification
  - High impact => must use low tolerances => more expensive
  - Low impact => could use higher tolerances => cheaper
- Find worst case scenario and determine if this is within specification
- Verify each domain (Time, Frequency, DC)

# Driver ADC input filter circuit



# Sensitivity Analysis Results

- Designed for 1k Bandwidth
- Calculated Min and Max Bandwidth: 841 and 1.25k  
*(based on 10% tolerance)*
- No Impact of Cs on Bandwidth

Sensitivity Component Filter = [ * ]							
	Component	Parameter	Original	@Min	@Max	Rel Sensitivity	Linear
▶	C4	VALUE	4.7000u	5.1700u	4.2300u	-9.7833	99
	R3	VALUE	33.2000	36.5200	29.8800	-9.7834	99
	Cs	VALUE	3p	3.9000p	3p	-6.4936u	< MIN >
Specifications							
	On/Off	Profile	Measurement	Original	Min	Max	
▶	<input checked="" type="checkbox"/>	ac.sim	Cutoff_Lowpass_3dB(V(C4:2))	1.0176k	841.0630	1.2563k	
Click here to import a measurement created within PSpice...							

# Use of EDA Tools

## *Reliability: Maximum Operation Conditions*

- Check Against Maximum Operation Conditions
  - Stress Analysis, or also called 'Smoke'
- Based on Transient simulation of a real-life scenario
- Automation of many measurements
  - Peak Voltage/Currents
  - Max breakdown voltage
  - C-E voltages
  - Max Power dissipation
  - Junction temperatures

# Use of EDA Tools

## *Reliability: Maximum Operation Conditions*

- PSpice is the only spice simulator that supports smoke analysis
- PSpice models have Smoke parameters built-in
- It's customizable
  - Take datasheet values

**Absolute Maximum Ratings** T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	FQT7N10L	Unit
V <sub>DSS</sub>	Drain-Source Voltage	100	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>A</sub> = 25°C)	1.7	A
	- Continuous (T <sub>A</sub> = 70°C)	1.36	A
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	6.8	A
V <sub>GSS</sub>	Gate-Source Voltage	± 20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	50	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	1.7	A
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	0.2	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	6.0	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C)	2.0	W
	- Derate above 25°C	0.016	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

### Smoke Parameters

These are Device Maximum Operating condition parameters required for Smoke Analysis

Device Max Ops	Description	Value	Unit
IG	Max gate current		A
ID	Max drain current	1.7	A
VDG	Max D-G voltage		V
VDS	Max D-S voltage	100	V
VGSF	Max forward VGS	20	V
VGSR	Max reverse VGS		V
PDM	Max pwr dissipation	2	W
TJ	Max junction temp.	150	°C
RJC	J-C thermal resist.		°C/W
RCA	C-A thermal resist.		°C/W

# Use of EDA Tools

## Reliability: Smoke results

Smoke - crowbar.sim [ No Derating ] Component Filter = [ * ]								
Component	Parameter	Type	Rated Value	% Derating	Max Derati...	Measured...	% Max	
X1	Maximum power dissipation	Average	1.4000	0	0	3.2036	< MAX >	
X1	Maximum junction temperature	Peak	125	100	125	7.1623k	5730	
X1	Maximum junction temperature	Average	125	100	125	251.2487	201	
X1	Max G-C voltage	Peak	6	100	6	6.2755	105	
X1	Max anode current	Peak	15	100	15	12.6227	85	
U2	Max forward VGS	Peak	20	100	20	14.8416	75	
U4	Rated Switch Contact Voltage	Peak	24	100	24	16.3930	69	
U2	Max drain current	Peak	1.7000	100	1.7000	738.6560m	44	
R4	Maximum breakdown temperature	Peak	200	100	200	72.2392	37	
U4	Rated Switch Contact Voltage	Average	24	100	24	7.8788	33	
U4	Rated Switch Current	Peak	40	100	40	12.6962	32	
R3	Maximum breakdown temperature	Peak	200	100	200	63.8574	32	
X1	Max A-C voltage	Peak	50	100	50	15.1776	31	
U3	Max anode current	Peak	20m	100	20m	5.1242m	26	
R5	Maximum breakdown temperature	Peak	200	100	200	42.7828	22	
U3	Max G-C voltage	Peak	6	100	6	1.2611	22	
U3	Maximum junction temperature	Peak	150	100	150	29.0662	20	
R3	Maximum breakdown temperature	Average	200	100	200	38.7861	20	

# Use of EDA Tools

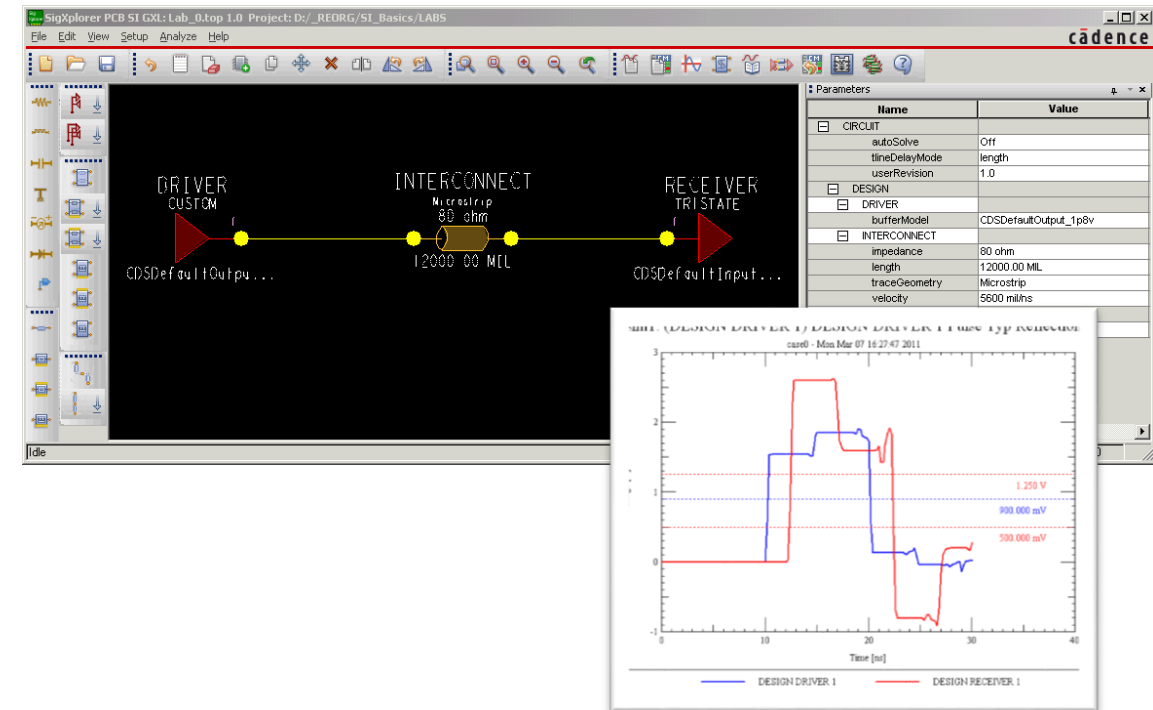
- Mixed Signal Circuit Simulation
  - Why simulation
  - Simulation models
  - Reliability Analysis
- PCB Design
  - Constraints
  - Multi board verification
  - 3D View



# Use of EDA Tools

## *Create constraints*

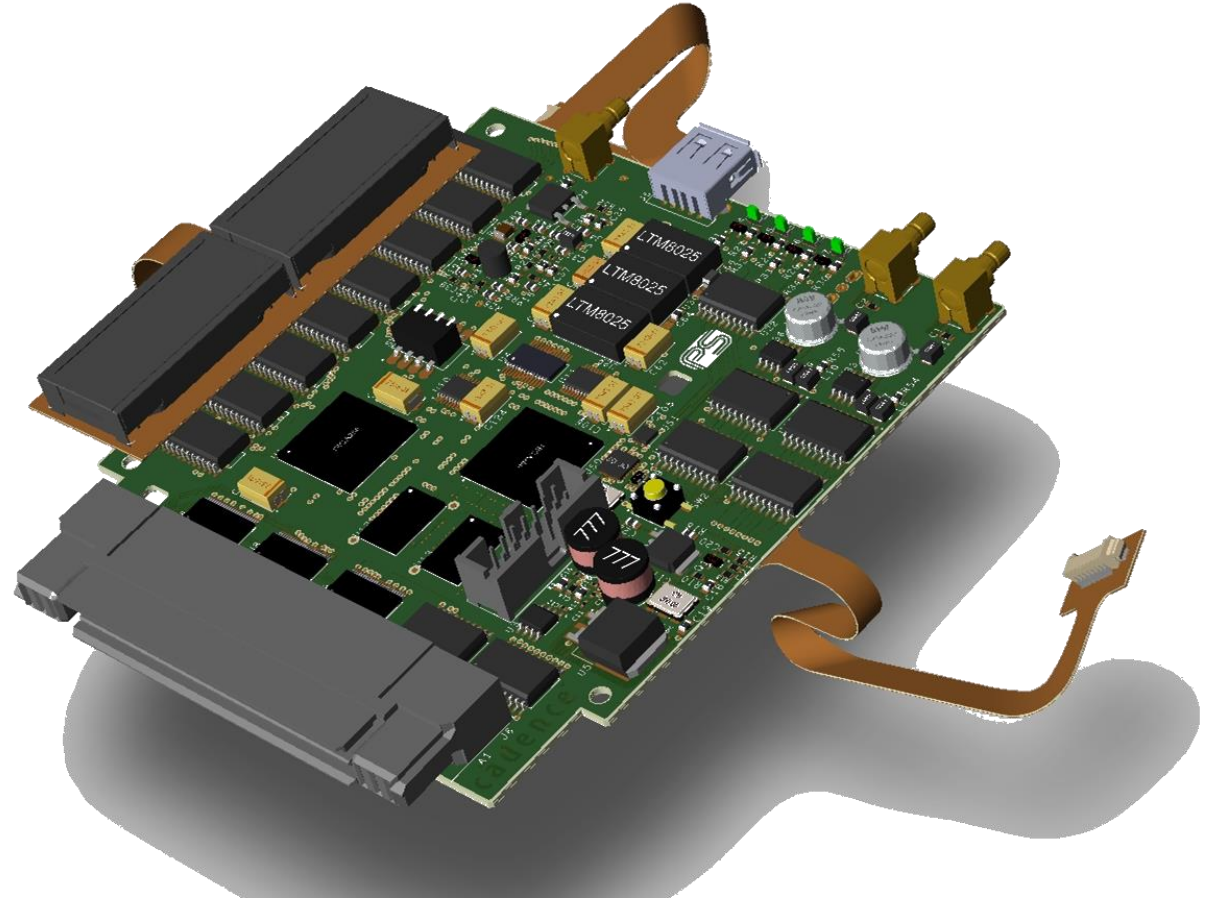
- With help of Simulation results
  - Currents -> Trace Width
  - Voltage levels -> Trace to Trace spacing
- With help of Signal topology study
  - Impedance mismatch -> Reflection
  - Highspeed -> Differential pair, matching length and phase.
- Start constraining at Schematic level



# Use of EDA Tools

## *PCB Design, 3D view*

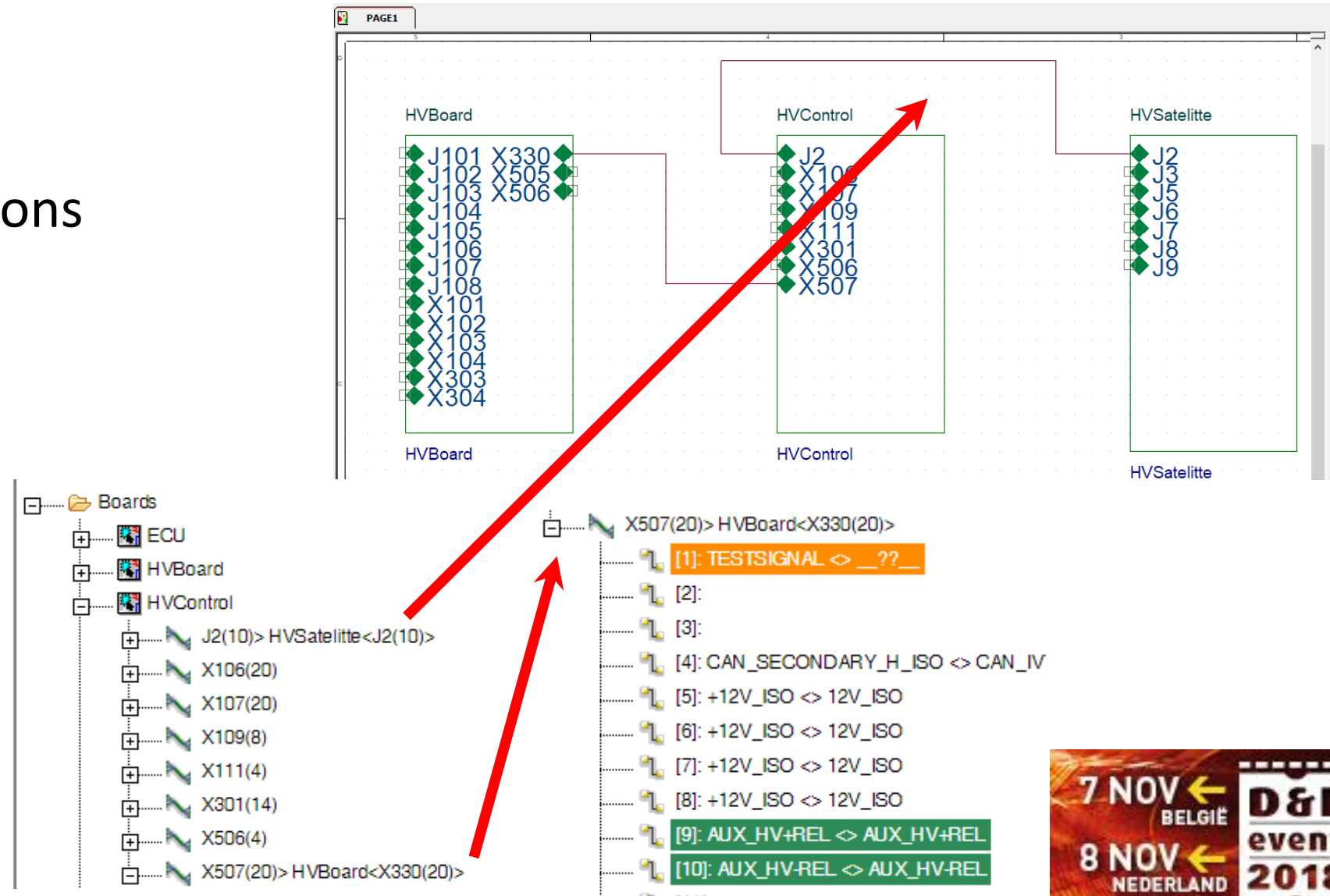
- Footprint verification
- Height verification



# Use of EDA Tools

## *Multi board, interconnect verification*

- Multi board project
  - Name of board
  - High level connections
- Connection Analysis
  - Number of pins
  - Net naming
- Color highlighting
  - Matching, Missing connections



# Use of EDA Tools

## *Summary*

- One vendor
  - PSpice driven layout, set the right constraints
  - One schematic environment to drive both simulation and multi PCB-design
- Powerful simulation capabilities beyond regular spice simulation
  - Smoke
- PCB
  - Unique centralized constraint management
  - Integrated verification



# Resulting PCB

- After simulation did we have any problems?
- Is it safe to drive the bike?
- Is the bike fast?



# Race Results

11-12 augustus 2018	Donington Park	Verenigd Koninkrijk	P2
31-1 september 2018	Assen	Nederland	P1
5-6 oktober 2018	Anglesey	Verenigd Koninkrijk	P1



# European Champions



# More information

- Visit our booth: 22
- See the real thing, an electric superbike
- Thanks for your attention



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